

PATENT ASSIGNMENT

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SUBMISSION TYPE:

NEW ASSIGNMENT

NATURE OF CONVEYANCE:

ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Junichi HANNA	11/26/2010
Isao SUZUMURA	11/23/2010
Mieko MATSUMURA	12/10/2010
Mutsuko HATANO	12/14/2010
Kenichi ONISAWA	12/01/2010
Masatoshi WAKAGI	12/01/2010
Etsuko NISHIMURA	11/29/2010
Akiko KAGATSUME	12/07/2010

RECEIVING PARTY DATA

Name:	Hitachi, Ltd.
Street Address:	6-6, Marunouchi 1-chome, Chiyoda-ku
City:	Tokyo
State/Country:	JAPAN

Name:	Tokyo Institute of Technology
Street Address:	12-1, O-okayama 2-chome
City:	Meguro-ku, Tokyo
State/Country:	JAPAN
Postal Code:	152-8550

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13001428

CORRESPONDENCE DATA

Fax Number: (703)610-8686

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501391237

PATENT
REEL: 025542 FRAME: 0942

CH \$40.00 13001428

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ATTORNEY DOCKET NUMBER:

XA-11764/T3381-18115US01

NAME OF SUBMITTER:

Dawn Minter

Total Attachments: 2

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ASSIGNMENT

(譲 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD.

and Tokyo Institute of Technology,

corporations organized under the laws of Japan,

located at 6-6, Marunouchi 1-chome, Chiyoda-ku, Tokyo, Japan

and 12-1, O-okayama 2-chome, Meguro-ku, Tokyo 152-8550, Japan

receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD.

and Tokyo Institute of Technology,

their successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR DEVICE, MANUFACTURING METHOD THEREOF,

AND DISPLAY APPARATUS USING THE SEMICONDUCTOR DEVICE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD.

and Tokyo Institute of Technology,

their successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD. and Tokyo Institute of Technology.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)
(発明者フルネームサイン)

Date Signed
(署名日)

1) _____ (Junichi HANNA)	_____
2) <u>Isao Suzumura</u> (Isao SUZUMURA)	<u>11/23/2010</u>
3) <u>Mieko Matsumura</u> (Mieko MATSUMURA)	<u>12/10/2010</u>
4) _____ (Mutsuko HATANO)	_____
5) <u>Kenichi Onisawa</u> (Kenichi ONISAWA)	<u>12/1/2010</u>
6) <u>Masatoshi Wakagi</u> (Masatoshi WAKAGI)	<u>12/1/2010</u>
7) <u>Etsuko Nishimura</u> (Etsuko NISHIMURA)	<u>11/29/2010</u>
8) <u>Akiko Kagatsune</u> (Akiko KAGATSUNE)	<u>12/7/2010</u>
9) _____	_____
10) _____	_____

PATENT

REEL: 025542 FRAME: 0944

ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

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AND DISPLAY APPARATUS USING THE SEMICONDUCTOR DEVICE**

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and Tokyo Institute of Technology,

their successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD. and Tokyo Institute of Technology.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)
(発明者フルネームサイン)

Date Signed
(署名日)

1) Jun-ichi Hanna (Junichi HANNA)

2010/11/26

2) _____ (Isao SUZUMURA)

3) _____ (Mieko MATSUMURA)

4) Mutsuko Hatano (Mutsuko HATANO)

2010/12/14

5) _____ (Kenichi ONISAWA)

6) _____ (Masatoshi WAKAGI)

7) _____ (Etsuko NISHIMURA)

8) _____ (Akiko KAGATSUME)

9) _____

10) _____

PATENT

RECORDED: 12/28/2010

REEL: 025542 FRAME: 0945